

# MM54HC133/MM74HC133 13-Input NAND Gate

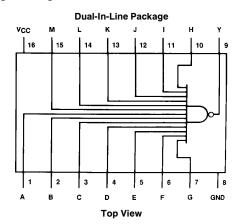
### **General Description**

This NAND gate utilizes advanced silicon-gate CMOS technology to achieve operating speeds similar to LS-TTL gates with the low power consumption of standard CMOS integrated circuits. All gates have buffered outputs. All devices have high noise immunity and the ability to drive 10 LS-TTL loads. The 54HC/74HC logic family is functionally as well as pin-out compatible with the standard 54LS/74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to  $V_{\rm CC}$  and ground.

#### **Features**

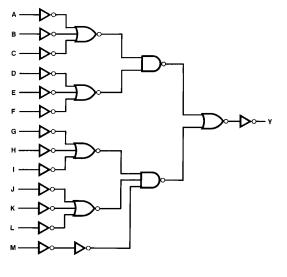
- Typical propagation delay: 20 ns
- Wide power supply range: 2-6V
- Low quiescent current: 20 µA maximum (74HC Series)
- Low input current: 1 µA maximum
- Fanout of 10 LS-TTL loads

### **Connection and Logic Diagrams**



TL/F/5134-1

#### Order Number MM54HC133 or MM74HC133



# Absolute Maximum Ratings (Notes 1 & 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage (V <sub>CC</sub> )	-0.5 to $+7.0$ V
DC Input Voltage (V <sub>IN</sub> )	$-1.5$ to $V_{CC} + 1.5V$
DC Output Voltage (V <sub>OUT</sub> )	$-0.5$ to $V_{CC} + 0.5V$
Clamp Diode Current (I <sub>IK</sub> , I <sub>OK</sub> )	$\pm$ 20 mA
DC Output Current, per pin (I <sub>OUT</sub> )	$\pm$ 25 mA
DC V <sub>CC</sub> or GND Current, per pin (I <sub>CC</sub> )	$\pm$ 50 mA
Storage Temperature Range (T <sub>STG</sub> )	$-65^{\circ}\text{C to } + 150^{\circ}\text{C}$

Power Dissipation (P<sub>D</sub>)

(Note 3) 600 mW S.O. Package only 500 mW

Lead Temperature (T<sub>L</sub>)

(Soldering 10 seconds) 260°C

### **Operating Conditions**

Supply Voltage (V <sub>CC</sub> )	Min 2	<b>Max</b> 6	Units V
DC Input or Output Voltage $(V_{IN}, V_{OUT})$	0	$V_{CC}$	V
Operating Temp. Range (T <sub>A</sub> ) MM74HC MM54HC	-40 -55	+85 +125	°C
$ \begin{array}{ll} \text{Input Rise or Fall Times} \\ (t_{r},t_{f}) & V_{CC}\!=\!2.0V \\ & V_{CC}\!=\!4.5V \\ & V_{CC}\!=\!6.0V \end{array} $		1000 500 400	ns ns ns

#### **DC Electrical Characteristics** (Note 4)

Symbol	bol Parameter	Conditions	v <sub>cc</sub>	T <sub>A</sub> =	= 25°C	74HC T <sub>A</sub> = -40 to 85°C	54HC T <sub>A</sub> = -55 to 125°C	Units
				Typ Guaranteed Limits				
$V_{\text{IH}}$	Minimum High Level Input Voltage		2.0V 4.5V 6.0V		1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V V V
V <sub>IL</sub>	Maximum Low Level Input Voltage**		2.0V 4.5V 6.0V		0.5 1.35 1.8	0.5 1.35 1.8	0.5 1.35 1.8	V V V
V <sub>OH</sub>	Minimum High Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 20 \mu A$	2.0V 4.5V 6.0V	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V V V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 4.0 \text{ mA}$ $ I_{OUT}  \le 5.2 \text{ mA}$	4.5V 6.0V	4.2 5.7	3.98 5.48	3.84 5.34	3.7 5.2	V V
V <sub>OL</sub>	Maximum Low Level Output Voltage	$V_{IN} = V_{IH}$ $ I_{OUT}  \le 20 \mu A$	2.0V 4.5V 6.0V	0 0 0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V V V
		$V_{IN} = V_{IH}$ $ I_{OUT}  \le 4.0 \text{ mA}$ $ I_{OUT}  \le 5.2 \text{ mA}$	4.5V 6.0V	0.2 0.2	0.26 0.26	0.33 0.33	0.4 0.4	V
I <sub>IN</sub>	Maximum Input Current	V <sub>IN</sub> =V <sub>CC</sub> or GND	6.0V		±0.1	±1.0	±1.0	μΑ
I <sub>CC</sub>	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu A$	6.0V		2.0	20	40	μΑ

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: -12 mW/°C from 65°C to 85°C; ceramic "J" package: -12 mW/°C from 100°C to 125°C.

Note 4: For a power supply of 5V  $\pm$  10% the worst case output voltages ( $V_{OH}$ , and  $V_{OL}$ ) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case  $V_{IH}$  and  $V_{IL}$  occur at  $V_{CC}$ =5.5V and 4.5V respectively. (The  $V_{IH}$  value at 5.5V is 3.85V.) The worst case leakage current ( $I_{IN}$ ,  $I_{CC}$ , and  $I_{OZ}$ ) occur for CMOS at the higher voltage and so the 6.0V values should be used.

<sup>\*\*</sup>V<sub>IL</sub> limits are currently tested at 20% of V<sub>CC</sub>. The above V<sub>IL</sub> specification (30% of V<sub>CC</sub>) will be implemented no later than Q1, CY'89.

# AC Electrical Characteristics $V_{CC} = 5V$ , $T_A = 25^{\circ}C$ , $C_L = 15$ pF, $t_r = t_f = 6$ ns

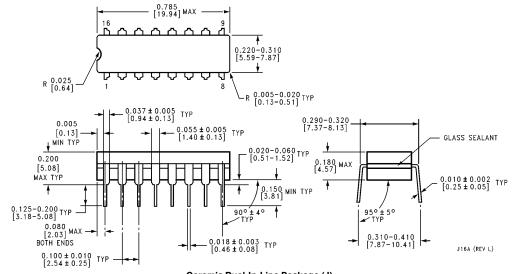
Symbol	Parameter	Conditions	Тур	Guaranteed Limit	Units
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay		20	30	ns

# $\textbf{AC Electrical Characteristics} \ \ V_{CC} = 2.0 \ \ \text{to 6.0V}, \ C_L = 50 \ \ \text{pF}, \ t_f = t_f = 6 \ \text{ns (unless otherwise specified)}$

Symbol	Parameter	Conditions	v <sub>cc</sub>	T <sub>A</sub> = 25°C		74HC T <sub>A</sub> = -40 to 85°C	54HC T <sub>A</sub> = -55 to 125°C	Units
				Тур		Guaranteed Limits		
t <sub>PHL</sub> ,	Maximum Propagation		2.0V	66	160	190	220	ns
t <sub>PLH</sub>	Delay		4.5V	23	35	42	49	ns
			6.0V	18	30	36	42	ns
t <sub>TLH</sub> ,	Maximum		2.0V	25	75	95	110	ns
t <sub>THL</sub>	Output Rise and		4.5V	7	15	19	22	ns
	Fall Time		6.0V	6	13	16	19	ns
C <sub>PD</sub>	Power Dissipation Capacitance (Note 5)			34				pF
C <sub>IN</sub>	Maximum Input Capacitance			5	10	10	10	pF

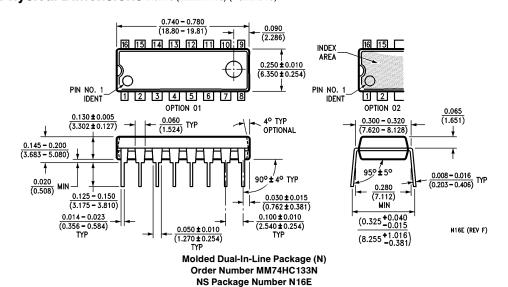
Note 5: C<sub>PD</sub> determines the no load dynamic power consumption, P<sub>D</sub>=C<sub>PD</sub> V<sub>CC</sub><sup>2</sup> f+I<sub>CC</sub> V<sub>CC</sub>, and the no load dynamic current consumption, I<sub>S</sub>=C<sub>PD</sub> V<sub>CC</sub> f+I<sub>CC</sub>.

# Physical Dimensions inches (millimeters)



Ceramic Dual-In-Line Package (J) Order Number MM54HC133J or MM74HC133J NS Package Number J16A

### Physical Dimensions inches (millimeters) (Continued)



#### LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.



National Semiconductor Corporation 1111 West Bardin Road Arlington, TX 76017 Tel: 1(800) 272-9959 Fax: 1(800) 737-7018 National Semiconductor Europe

Fax: (+49) 0-180-530 85 86 Email: cnjwge@tevm2.nsc.com Deutsch Tel: (+49) 0-180-530 85 85 English Tel: (+49) 0-180-532 78 32 Français Tel: (+49) 0-180-532 93 58 Italiano Tel: (+49) 0-180-534 16 80 National Semiconductor Hong Kong Ltd. 13th Floor, Straight Block, Ocean Centre, 5 Canton Rd. Tsimshatsui, Kowloon Hong Kong Tel: (852) 2737-1600 Fax: (852) 2736-9960 National Semiconductor Japan Ltd. Tel: 81-043-299-2309 Fax: 81-043-299-2408